

# LITEON® LITE-ON TECHNOLOGY CORPORATION

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### LED DISPLAY

# LTS-5825CKG-PST1 **DATA SHEET**

<u>ITEM</u>	<u>Description</u>	By	DATE
1	New Spec	Reo Lin	2012/06/06
2	Revised P/N name from LTS-5825CKG-P-ST1 to LTS-5825CKG-PST1	Reo Lin	2012/06/19
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		_	_

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#### **FEATURES**

- \*0.56 inch (14.22 mm) DIGIT HEIGHT
- \*CONTINUOUS UNIFORM SEGMENTS
- **\*LOW POWER REQUIREMENT**
- \*EXCELLENT CHARACTERS APPEARANCE
- \*HIGH BRIGHTNESS & HIGH CONTRAST
- \*WIDE VIEWING ANGLE
- **\* SOLID STATE RELIABILITY**
- \*CATEGORIZED FOR LUMINOUS INTENSITY

#### **DESCRIPTION**

The LTS-5825CKG-PST1 is a 0.56 inch (14.22 mm) digit height single digit SMD display. The devices utilize AlInGaP Green LED chips, which are made from AlInGaP on a non-transparent GaAs substrate. The display has black face and white segments.

#### **DEVICE**

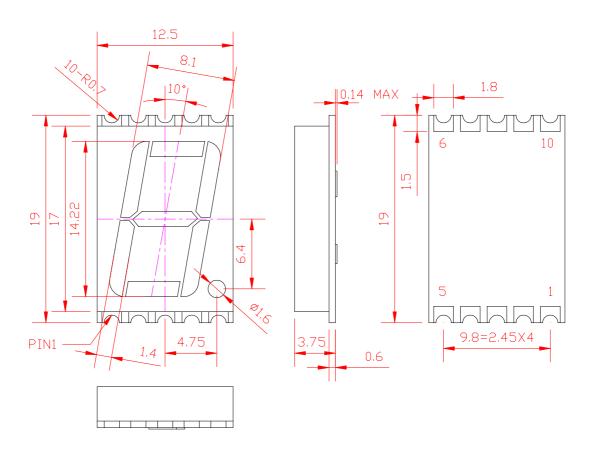
PART NO.	DESCRIPTION		
AlInGaP green			
LTS-5825CKG-PST1	Common Anode		

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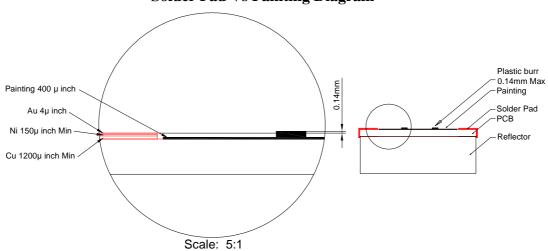


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#### PACKAGE DIMENSIONS



#### **Solder Pad Vs Painting Diagram**



#### NOTES:

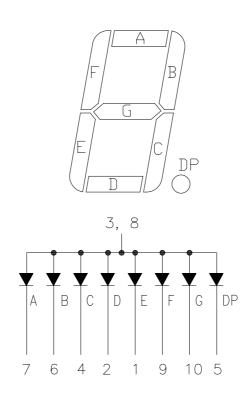
- 1. Plastic pins' burr maximum 0.14 mm, warping of PCB maximum 0.06 mm.
- 2. All dimensions are in millimeters. Tolerances are  $\pm$  0.25mm (0.01") unless otherwise noted.
- 3. Solder pad materials and thickness: Cu:  $1200 \mu$  inch Ni: Min  $150 \mu$  inch Au:  $4 \mu$  inch.

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# INTERNAL CIRCUIT DIAGRAM



### **PIN CONNECTION**

No.	CONNECTION
1	CATHODE E
2	CATHODE D
3	COMMON ANODE
4	CATHODE C
5	CATHODE DP
6	CATHODE B
7	CATHODE A
8	COMMON ANODE
9	CATHODE F
10	CATHODE G

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#### ABSOLUTE MAXIMUM RATING AT Ta = 25°C

PARAMETER	MAXIMUM RATING	UNIT		
Power Dissipation Per Segment	70	mW		
Peak Forward Current Per Segment	60	mA		
(Frequency 1Khz,10% duty cycle)	60			
Continuous Forward Current Per Segment	25	mA		
Forward Current Derating from 25 °C	0.28	$mA/^{\circ}C$		
Operating Temperature Range -40 °C to +105 °C				
Storage Temperature Range -40°C to +105°C				
Soldering Conditions: 1/16 inch Below Seating Plane for 3 Seconds at 260°C				

# ELECTRICAL / OPTICAL CHARACTERISTICS AT Ta = 25°C

PARAMETER	SYMBOL	MIN.	TYP.	MAX.	UNIT	TEST CONDITION
Luminous Intensity	IV	501	1700		$\mu$ cd	I <sub>F</sub> =1mA
Peak Emission Wavelength	λр		571		nm	I <sub>F</sub> =20mA
Spectral Line Half-Width	Δλ		15		nm	I <sub>F</sub> =20mA
Dominant Wavelength	λd		572		nm	I <sub>F</sub> =20mA
Forward Voltage Per Segment	$V_{\mathrm{F}}$		2.05	2.6	V	I <sub>F</sub> =20mA
Reverse Current Per Segment <sup>(2)</sup>	Ir			100	uA	V <sub>R</sub> =5V
Luminous Intensity Matching Ratio	Iv-m			2:1		I <sub>F</sub> =1mA

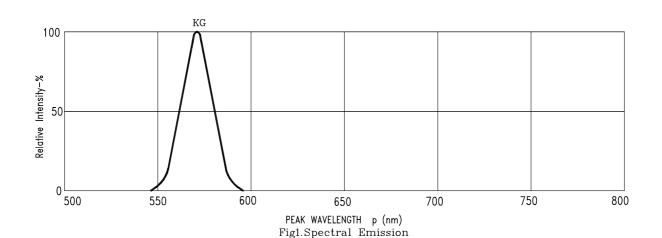
#### Note:

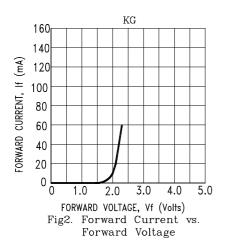
- 1. Luminous intensity is measured with a light sensor and filter combination that approximates the CIE (Commision Internationale De L'Eclairage) eye-response curve.
- 2. Reverse voltage is only for IR test. It can not continue to operate at this situation.
- 3. Cross talk specification  $\leq 2.5 \%$

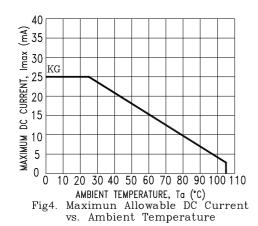
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#### TYPICAL ELECTRICAL / OPTICAL CHARACTERISTIC CURVES

(25°C Ambient Temperature Unless Otherwise Noted)







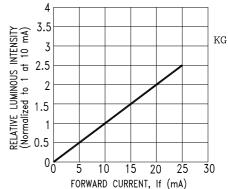
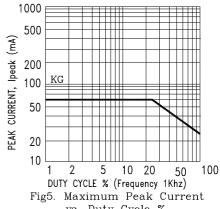


Fig3. Relative Luminous Intensity vs. DC Forward Current



vs. Duty Cycle %

NOTE: KG=AlInGaP Green

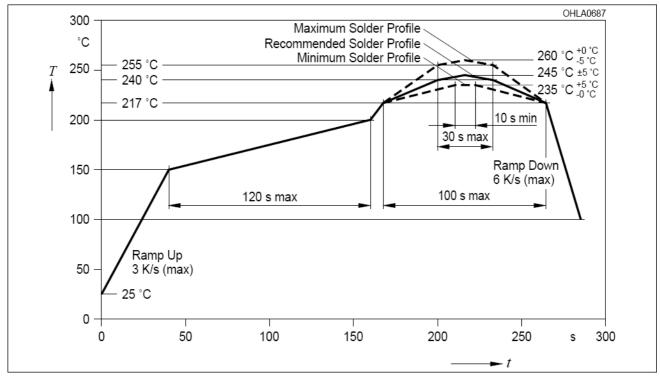
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#### SMT SOLDERING INSTRUCTION

(Number of reflow process shall be less than 2 times, and cooling process to normal temperature is required between the first and the second soldering process)



Note:

1. Recommended soldering condition:

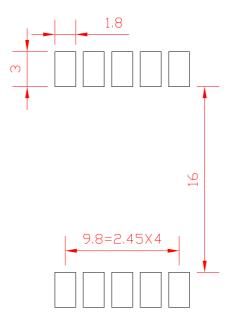
Reflow Soldering (Two times only)		Soldering Iron (One time only)		
Pre-heat:	120~150°C	Temperature 300°C Max.		
Pre-heat time:	120sec. Max.	Soldering time	3sec. Max.	
Peak temperature:	260°C Max.			
Soldering time:	5sec. Max.			

2. Number of reflow process shall be less than 2 times, and cooling process to normal temperature is required between the first and the second soldering process.

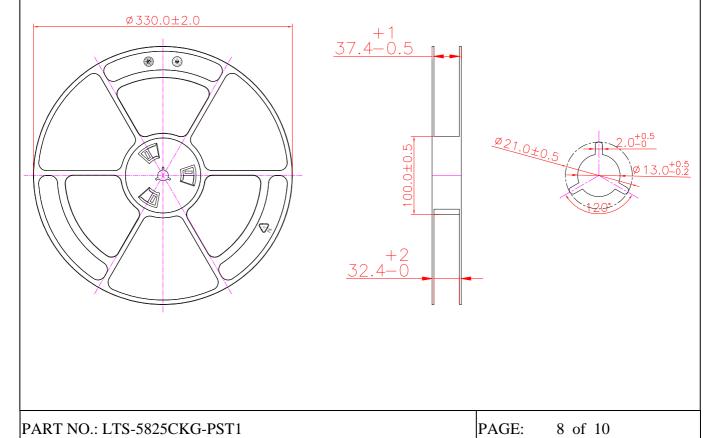
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# RECOMMENDED SOLDERING PATTERN (UNIT: MM)



# PACKING REEL DIMENSIONS



BNS-OD-C131/A4



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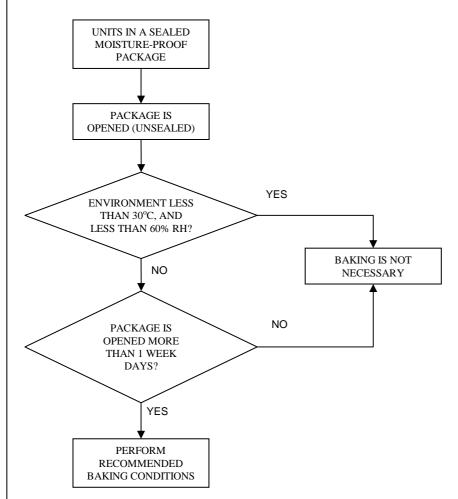
# PACKING CARRIER DIMENSIONS 1. Taping parts: $1.75 \pm 0.10$ 4.00±0.10 2.00±0.10 $20.00\pm0.10$ $\emptyset 1.50^{+0.1}_{-0}$ <del>-</del> - $.40\pm0.10$ 32.00±0.30 $\oplus$ 0 **+ + + + + + + +** + Ø2.00MIN 12.80 4.40 1. 10 sprocket hole pitch cumulative tolerance $\pm 0.20$ . 2. Carrier camber is within 1 mm in 250 mm. 3. Material : Black Conductive Polystyrene Alloy. 4. All dimensions meet EIA-481-D requirements. 5. Thickness: 0.30±0.05mm. 6. Packing length per 22" reel: 44.5 Meters.(1:3) 7. Component load per 13" reel: 700 pcs. 2. Trailer part/ Leader part: (40mm MIN.) (400mm MIN.) -EMPTY--PARTS MOUNTED--LEADER----EMPTY-(40mm MIN.) DIRECTION OF PULLING OUT PART NO.: LTS-5825CKG-PST1 PAGE: 9 of 10



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### MOISTURE PROOF PACKAGING

All N/D SMD displays are shipped in moisture proof package. The displays should be stored at 30°C or less and 90% RH or less. Once the package opened, moisture absorption begins.



#### **Baking Conditions**

If the parts are not stored in dry conditions, they must be baked before reflow to prevent damage to the parts.

Package	Temperature	Time
In Reel	60°C	≧48hours
In Bulk	100°C	≧4hours
III DUIK	125 °C	≥2hours

Baking should only be done once.

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